

10/719,876

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2	("20010040117").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/24 17:55
L2	1	1 and opaque	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/24 17:56
L3	1	2 and laser and mark\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/24 18:05
L4	18	(("6080602") or ("6607970") or ("6221751") or ("20010040117") or ("6060373") or ("20020009826") or ("20020097302") or ("6534387") or ("6573156")).PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/24 18:06
L5	3	4 and test\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/24 18:07
S1	58	((("5138434") or ("5686317") or ("5851911") or ("5863813") or ("5888883") or ("5897337") or ("5904546") or ("6013948") or ("6051875") or ("6060373") or ("6074896") or ("6080602") or ("6087845") or ("6107109") or ("6114240") or ("6130111") or ("6136137") or ("6150717") or ("6153448") or ("6169329") or ("6177295") or ("6180504") or ("6221751") or ("6233185") or ("6281131") or ("6294837") or ("6313531") or ("6326698") or ("6338980")).PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/23 14:07
S2	17	((("6107164") or ("6350664") or ("6353267") or ("6524890") or ("6534387") or ("6579748") or ("6607970") or ("6649445")).PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/22 18:06
S3	1134	((438/460) or (438/462)).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/23 14:11

S4	823	S3 and @ad<"20020306"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/24 12:33
S5	137	S4 and (etch\$3 near5 (back backside rear bottom))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/23 14:14
S6	101	S5 and mask\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/23 14:23
S7	87	S6 and wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/23 14:24
S8	1134	((438/460) or (438/462)).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/24 12:33
S9	823	S8 and @ad<"20020306"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/24 13:00
S10	3	S9 and KOH and TMAH	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/24 13:06
S11	777	(silicon wafer substrate) and KOH and TMAH and @ad<"20020306"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/24 13:07
S12	605	S11 and (dic\$3 cut\$4 saw\$3 separat\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/24 13:08
S13	299	S11 and ((dic\$3 cut\$4 saw\$3 separat\$4) same etch\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/24 13:11

S14	158	S11 and ((dic\$3 cut\$4 saw\$3 separat\$4) near10 etch\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/24 13:11
S15	123	S11 and ((dic\$3 separat\$4) near10 etch\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/24 13:46
S16	635	(stencil near8 (polymer resin epoxy encapsula\$4 organic)) and @ad<"20020306" and (substrate wafer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/24 13:49
S17	1	S16 and (tape near5 opaque)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/24 13:50
S18	21	S16 and (heat adj (sink spreader))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/24 13:52
S19	24	S16 and (heat adj (sink spreader))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/24 14:31
S20	1069	(tape near5 opaque) and @ad<"20020306"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/24 15:31
S21	15	S20 and (laser near6 (mark\$3 label\$4))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/24 15:09
S22	24	S20 and (laser same (mark\$3 label\$4))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/24 15:17
S23	58	S20 and ((laser radiat\$4 irradiat\$4) same (mark\$3 label\$4))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/24 15:18

S24	119	((tape near5 opaque) same (laser radiat\$3 irradiat\$3)) and @ad<"20020306"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/24 15:51
S25	20100	((mark\$3 label\$4 identif\$4) near8 tape) and @ad<"20020306"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/24 15:53
S26	201	S25 and (opaque near5 tape)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/24 15:54
S27	67	S26 and (laser radiat\$4 irradiat\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/24 16:06
S28	264734	(semiconductor IC (integrated adj circuit) chip die dice) and ((label\$4 mark\$3) and @ad<"20020306"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/24 16:08
S29	34943	S28 and tape	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/24 16:07
S30	2739	(semiconductor IC (integrated adj circuit) chip die dice) and ((label\$4 mark\$3) near5 tape) and @ad<"20020306"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/24 16:24
S31	1215	S30 and (opaque transmit\$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/24 16:11
S32	354	S30 and opaque	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/24 16:12
S33	165	S32 and (laser radiat\$4 irradiat\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/24 16:12

S34	1654	(semiconductor IC (integrated adj circuit) chip dice) and ((label\$4 mark\$3) near5 tape) and @ad<"20020306"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/24 16:25
S35	871	S34 and (opaque transmit\$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/24 16:26
S36	303	S35 and (laser radiat\$4 irradiat\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/24 16:26
S37	144	S34 and opaque	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/24 16:27
S38	71	S37 and (laser radiat\$4 irradiat\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/24 16:35
S39	2	("5937270").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/24 16:47
S40	0	S39 and tap\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/24 17:55